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**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION**

Generic Copy

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**24 Aug 2007**

**SUBJECT: ON Semiconductor Final Product/Process Change Notification #16034**

**TITLE: FPCN for Qualification of UDFN/UQFN 0.5mm Package Thickness (1.0x1.2mm to 1.8x2.6mm) at ON Seremban**

**PROPOSED FIRST SHIP DATE: 24 Nov 2007**

**AFFECTED CHANGE CATEGORY(S): ON Semiconductor Assembly & Test**

**AFFECTED PRODUCT DIVISION(S): Analog Switch Products**

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or Kathleen Van Tyne <[k.vantyne@onsemi.com](mailto:k.vantyne@onsemi.com)>

**SAMPLES:** Contact your local ON Semiconductor Sales Office

**ADDITIONAL RELIABILITY DATA:** Available

Contact your local ON Semiconductor Sales Office or Laura Rivers <[laura.rivers@onsemi.com](mailto:laura.rivers@onsemi.com)>

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

**DESCRIPTION AND PURPOSE:**

This is a Final PCN (Product Change Notice) to notify customers that the changes described in PCN#15676 (which can be found at [www.onsemi.com](http://www.onsemi.com)), have been completed for the listed devices.

This is the Final PCN announcing the qualification of the ON Semiconductor facility located in Seremban, Malaysia as an additional assembly location for the 0.5mm thickness UQFN/UDFN packages for analog switches.

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Seremban is currently a qualified site for the assembly of 0.9mm thick QFN/DFN packages. There will be no changes in device functionality, case outline, or footprint. Reliability will continue to meet or exceed ON Semiconductor's highest standards. Upon expiration of this FPCN, all UDFN/UQFN 0.5MM Package Thickness (1.0x1.2 MM to 1.8x2.6MM) devices will be sourced from both the Seremban facility and the existing facility (UTAC, located in Bangkok, Thailand). Any new devices/derivatives package from same qfn platform released after publication of this Generic FPCN for a specific package style/die size will be qualified for assembly in both locations.

**RELIABILITY DATA SUMMARY:**

Qual Vehicle: NLAS3799BMUR2G (Largest package UQFN16L 1.8x2.6MM)

<b>Test</b>	<b>Conditions</b>	<b>Results</b>
HTOL	TA=150°C, 1008 hrs	0/231
HTB	TA=150°C, 1008 hrs	0/231
Preconditioning (PC)	MSL 1, 260° C	0/693
PC -Temp Cycle	-65/+150°C for 1000 cycles	0/231
PC -Autoclave	121°C/100%RH/15psig for 96hrs	0/231
PC -HAST	131°C/80%RH for 96 hrs	0/231
Solder Heat	260°C 10 seconds	0/35

**ELECTRICAL CHARACTERISTIC SUMMARY:**

All products' performance meets current datasheet specifications.

**CHANGED PART IDENTIFICATION:**

Products manufactured after the FPCN expiration date can be manufactured at either ON Seremban or UTAC Thailand locations. Assembly location code will be maintained for traceability.



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**AFFECTED DEVICE LIST:**

NLAS7222AMUTAG  
NLAS5223BMUR2G  
NLAS3799BMUR2G  
NLAS52231MUR2G  
NLAS5124MUR2G  
NLAS5123MUR2G  
NLAS5113MUTAG  
NLAS7222AMUR2G  
NLVHC1GT66MUR2G  
NLVHC1G66MUR2G